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Application Serial No. 09/756,971
Response to 02/05/04 OA

MI22-1572

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/756,971
Filing Date January 9, 2001
Inventor Salman Akram
Assignee Micron Technology, Inc.
Group Art Unit 2827
Examiner D.A. Zarneke
Attorney's Docket No. MI22-1572
Title: Methods of Forming Board-On-Chip Packages

RESPONSE TO FEBRUARY 5, 2004 OFFICE ACTION

To: Mail Stop Amendment
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

From: D. Brent Kenady
 Tel. 509-624-4276; Fax 509-838-3424
 Wells St. John P.S.
 601 West First Avenue, Suite 1300
 Spokane, WA 99201-3828

Responsive to the Office Action dated February 5, 2004, Applicant amends
and remarks as follows:

AMENDMENTS

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.